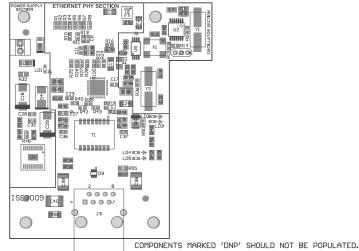
- 221 Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

 222 Inhese assemblies are ESD sensitive, ESD precautions shall be observed.

 233 Inhese assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ3 ■These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 ZZ4 ■These assemblies must comply uith workmanship standards IPC-A-610 Class 2, unless otherwise specified.

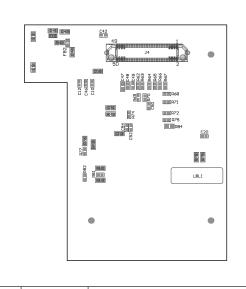


ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE BOARD #: TIDA-00207 REV: E1 SUN REV: Not In VersionControl

LAYER NAME : ASSEMBLIYEFOPlask

PLOT NAME = Top Assembly Drawing GENERATED : 9/23/2014 10:11:34 AM TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE BOARD #:

Bottom Assembly Drawing

TIDA-00207

REV: E1

SUN REU: Not In VersionControl Bottom Solder Mask

PLOT NAME =

GENERATED

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